

Features

- Frequency: 15GHz~17.5GHz
- Power Gain: 20dB
- Psat: 42dBm
- P.A.E.: 35%
- +28V @ 1.0A (Quiescent)
- Chip Size: 3.1mm×1.7mm×0.1mm

Electrical Specification (TA=+25°C, Vd=+28V, Vg=-3.2V)

Parameter	Min.	Typ.	Max.	Unit
Frequency	15~17.5			GHz
Power Gain	20	20.2		dB
Psat	42	42.2		dBm
P.A.E.	30	35		%
VSWRin		2.0	2.5	-
Dynamic Operating Current	1.8			A

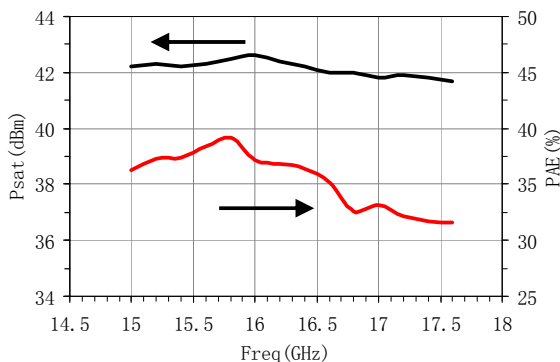
Note: 1) All chips have been on-chip 100% DC tested.
 2) Test Condition: Vd=+28V, Vg=-3.2V, pulse width 100μs, duty cycle 10%, P_{in}=22dBm.

Limited Rating Values

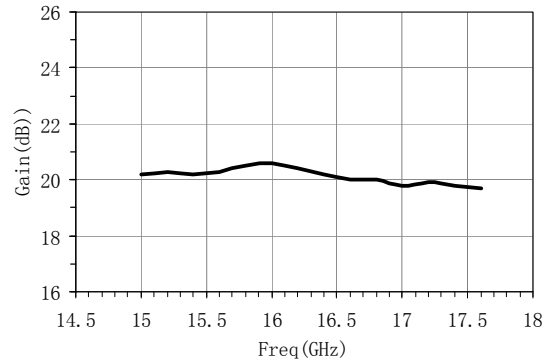
Max. Input Vd	+30V
Max. Input Power	+25dBm
Storage Temperature	-65°C ~ +150°C
Operating Temperature	-55°C ~ +125°C

Typical Testing Curves

Output Psat/Efficiency VS Frequency

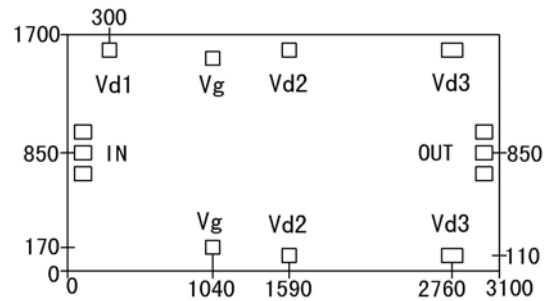


Power Gain VS Frequency



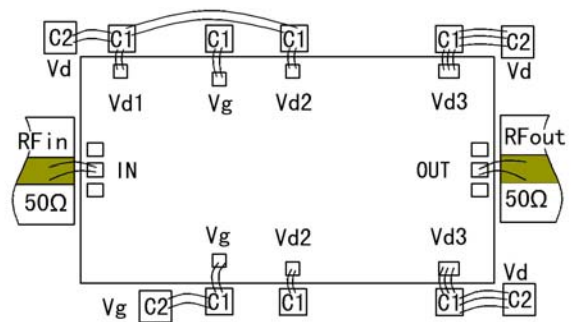
Dimensions and Outline

NC11601C-1517P16 outline



Note: The unit is um.
 Dimension of input/output pad: 100×120μm².
 Dimension of bias pad: 100×100μm².

Assembly Diagram



Note: External capacitor c=100pF, c2=0.01μF; A 0.01μF capacitor should be added to the gate bias. Gold bonding wire diameter: 25μm.

Attention

- 1) 2 bonding wires should be used for input/output. The length of the wires should be shorter than 350μm.
- 2) Bonding with 80/20 Au/Sn. The temperature should be lower than 300°C and the time should be less than 30 seconds.
- 3) Blocking capacitors in Input/Output are already integrated.
- 4) Antistatic protection should be taken.